

REMARKS

New claim 18 corresponds to former dependent claim 3, but the wording has been broadened. However, it is believed that the substance of what was indicated to be allowable is retained within new claim 18. Therefore, claim 18, and its dependent claims, should be in condition for allowance.

Claim 14 has been amended to include the subject matter of claim 15, indicated to be allowable, and, therefore, claim 14, as amended, should be in condition for allowance.

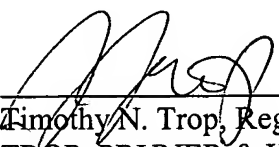
Claim 1 was rejected over the Jankowski reference. It is respectfully submitted that Jankowski does not teach forming a trench in each of two semiconductor substrates and combining the substrates in face-to-face abutment with the trenches in alignment with one another. Namely, the structure shown in Figure 9 and discussed at paragraph 44 of the Jankowski reference is very unclear. There is a structure 906 which, apparently, may be a silicon wafer. See paragraph 44, line 5. It is hard to say whether the channel 905 could be considered a trench since it goes completely through that structure 906.

It is unclear what other element could possibly be a semiconductor wafer. The element at the bottom is never explained. It is not clear what it is. It does not appear to be placed in face-to-face abutment with the structure 906 because intervening therebetween is the heater 910 and what looks like a spacer on the right side of the figure. Therefore, it does not appear that trenches are formed in two semiconductor substrates and that the substrates are combined in face-to-face abutment with the trenches in alignment with one another.

Therefore, reconsideration of the rejection of claim 1 is respectfully requested.

Respectfully submitted,

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